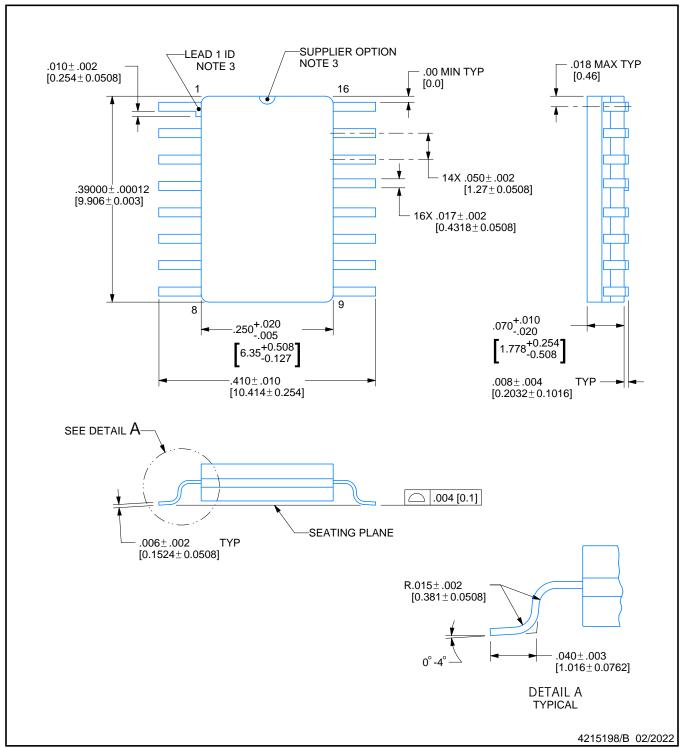


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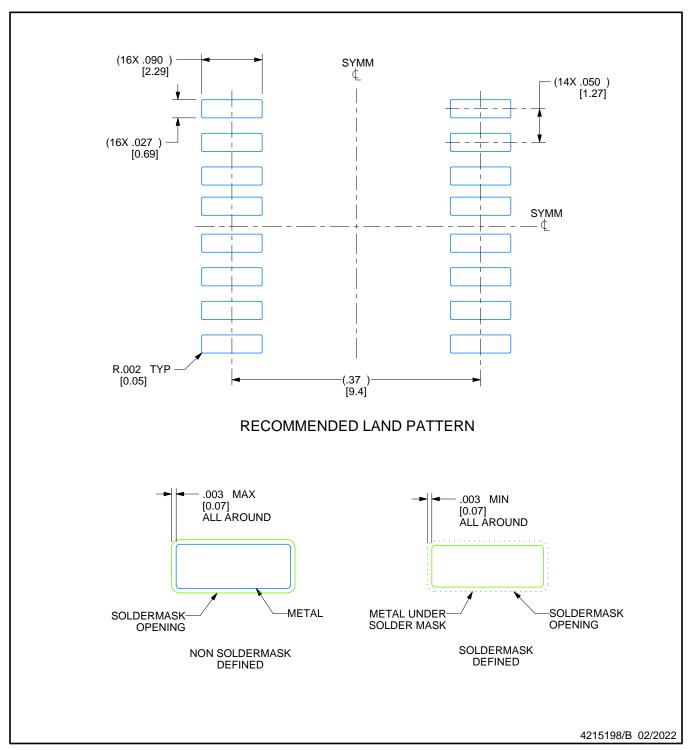


NOTES:

- 1. Controlling dimension is Inch. Values in [] are milimeters. Dimensions in () for reference only.
 2. For solder thickness and composition, see the "Lead Finish Composition/Thickness" link in the packaging section of the Texas Instruments website
- 3. Lead 1 identification shall be:
 - a) A notch or other mark within this area
 - b) A tab on lead 1, either side
- 4. No JEDEC registration as of December 2021



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